

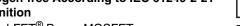
HY0720L-VB Datasheet

N-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^e	Q _g (Typ.)			
	0.028 at V _{GS} = 4.5 V	6 ^a				
20	0.042 at V _{GS} = 2.5 V	6 ^a	8.8 nC			
	0.050 at V _{GS} = 1.8 V	5.6				

FEATURES







- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



HALOGEN **FREE**

APPLICATIONS

- DC/DC Converters
- Load Switch for Portable Applications

	SOT-23		
G 1 S 2		3	D
	Top View		

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	20	V	
Gate-Source Voltage		V_{GS}	± 12	v	
	T _C = 25 °C		6 ^a		
Continuous Proin Current (T = 150 °C)	T _C = 70 °C] ,]	5.1		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	- I _D	5 ^{b, c}		
	T _A = 70 °C		4 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	20		
Continuous Source-Drain Diode Current	T _C = 25 °C	_	1.75		
Continuous Source-Diam Diode Current	T _A = 25 °C	l _S	1.04 ^{b, c}		
	T _C = 25 °C		2.1		
Maximum Power Dissipation	T _C = 70 °C	1 5	1.3	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	VV	
	T _A = 70 °C]	0.8 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	
Soldering Recommendations (Peak Temperature)		,	260		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R _{thJA}	80	100	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	40	60	O/ VV	

Notes:

- a. Package limited
- b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under steady state conditions is 125 $^{\circ}\text{C/W}.$
- e. Based on T_C = 25 °C.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	<u> </u>		,			
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	20			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		25		mV/°C
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 2.6		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	0.45		1.0	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA
		V _{DS} = 20 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 \text{ °C}$			10	μΑ
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	20			Α
		$V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		0.028		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 2.5 \text{ V}, I_D = 4.7 \text{ A}$		0.042		Ω
		$V_{GS} = 1.8 \text{ V}, I_D = 4.3 \text{ A}$	0.050			
Forward Transconductance ^a	9 _{fs}	V _{DS} = 10 V, I _D = 5.0 A		24		S
Dynamic ^b			L		L	
Input Capacitance	C _{iss}			865		
Output Capacitance	C _{oss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		105		pF
Reverse Transfer Capacitance	C _{rss}			55		
· ·		$V_{DS} = 10 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 5.0 \text{ A}$		12	18	1
Total Gate Charge	Qg	20 40 2		8.8	14	nC
Gate-Source Charge	Q_{gs}	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 5.0 \text{ A}$		1.1		
Gate-Drain Charge	Q_{gd}			0.7		
Gate Resistance	R_{g}	f = 1 MHz	0.5	2.4	4.8	Ω
Turn-On Delay Time	t _{d(on)}			8	16	
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		17	26	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 4$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		31	47	
Fall Time	t _f			8	16	ns
Turn-On Delay Time	t _{d(on)}			5	10	110
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.2 Ω		13	20	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong 4 \text{ A}, V_{GEN} = 5 \text{ V}, R_g = 1 \Omega$		21	32	
Fall Time	t _f			6	12	
Drain-Source Body Diode Characteristic	es				L	
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			1.75	
Pulse Diode Forward Current	I _{SM}				20	A
Body Diode Voltage	V_{SD}	I _S = 4 A, V _{GS} = 0 V		0.75	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			12	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}	I 4 A dI/dt 100 A/vo T 05 °C		5	10	nC
Reverse Recovery Fall Time	t _a	$I_F = 4 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 \text{ °C}$		7		
Reverse Recovery Rise Time				5		ns

Notes:

- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

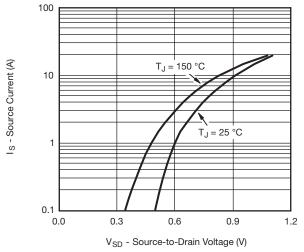


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

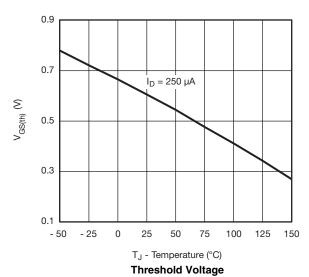


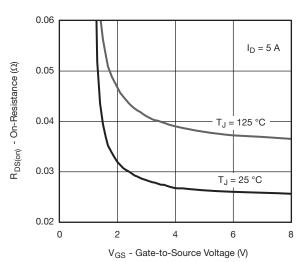


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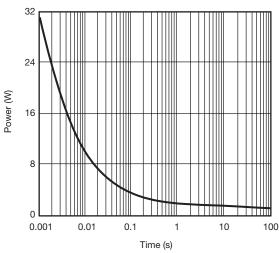


Source-Drain Diode Forward Voltage

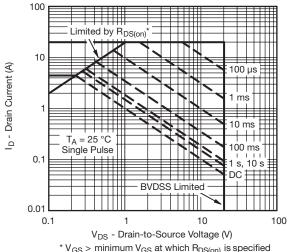




On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power (Junction-to-Ambient)

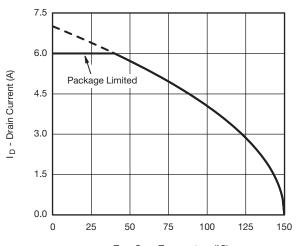


 * V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

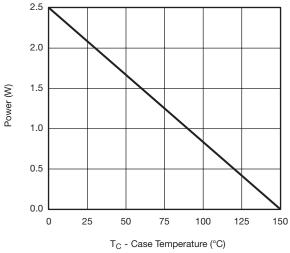


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



T_C - Case Temperature (°C)

Current Derating*







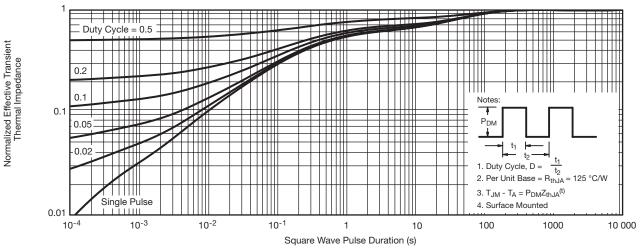
Power Derating, Junction-to-Ambient

^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

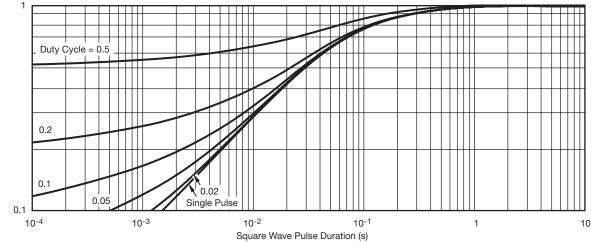
Normalized Effective Transient Thermal Impedance



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



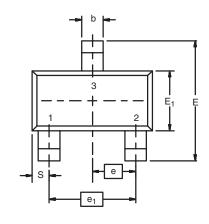
Normalized Thermal Transient Impedance, Junction-to-Ambient

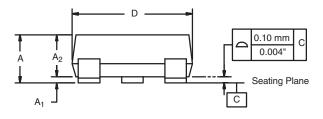


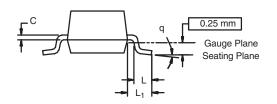
Normalized Thermal Transient Impedance, Junction-to-Foot



SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95	0.95 BSC		0.0374 Ref	
e ₁	1.90	1.90 BSC		8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01				

DWG: 5479



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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